MULTI-COM.PL



Planting kit BTP3 for BGA IC/SMD parts

Product ID: 513

Price: **63.54 EUR**

Product weight: **1.60 kg**

Description:

Planting kit BTP3 for BGA IC/SMD parts with solder station, discharge fun and BGA tin ball tools - best tools for enginners in GSM/DCS services.

Go to the product

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